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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: JOHN M. PEDERSEN ET AL.

APPLICATION NO.:

09/823.948

FILED:

MARCH 30, 2001

FOR: DRY CONTACT ASSEMBLIES, METHODS

FOR MAKING DRY CONTACT

ASSEMBLIES, AND PLATING MACHINES WITH DRY CONTACT ASSEMBLIES FOR

PLATING MICROELECTRONIC

WORKPIECES

EXAMINER: BRIAN L. MUTSCHLER

ART UNIT: 1753

CONF. No: 7598

| W.M. 6/11/03

Amendment in Response to Restriction Requirement

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 JUN 0 9 2003 TC 1700

Sir:

In response to the Office Action dated April 30, 2003, please amend the application as reflected in the following listing of claims.

Amendment to the Claims

- 1. (Original) A contact assembly for plating a layer on a microelectronic workpiece, comprising:
- a support member having an opening configured to receive a microelectronic workpiece;
- a contact system carried by the support member, the contact system having a plurality of electrically conductive contact members projecting inwardly into the opening;
- a shield carried by the support member to prevent electroplating solution from engaging the contact members, the shield projecting from the support member to